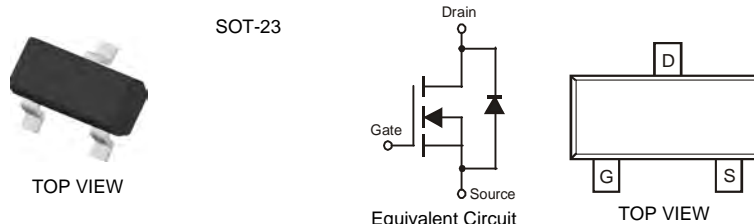


Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Lead, Halogen and Antimony Free, RoHS Compliant "Green" Device (Notes 2 and 4)**

Mechanical Data

- Case: SOT-23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.008 grams (approximate)



Maximum Ratings @T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Value | Units |
|--------------------------------------------|------------------|------------|-------|
| Drain-Source Voltage | V _{DSS} | 60 | V |
| Drain-Gate Voltage R _{GS} ≤ 1.0MΩ | V _{DGR} | 60 | V |
| Gate-Source Voltage | V _{GSS} | ±20 ±40 | V |
| Drain Current (Note 1) | I _D | Continuous | 500 |
| | | Pulsed | 800 |

Thermal Characteristics @T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Value | Units |
|-----------------------------------------|-----------------------------------|-------------|-------------|
| Total Power Dissipation (Note 1) | P _d | 300 1.80 | mW mW/°C |
| Thermal Resistance, Junction to Ambient | R _{θJA} | 417 | K/W |
| Operating and Storage Temperature Range | T _j , T _{STG} | -55 to +150 | °C |

Electrical Characteristics @T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|-------------------------------------|---------------------|-----|-----|-----|------|------------------------------------------------------------------------------------------------|
| OFF CHARACTERISTICS (Note 3) | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 60 | 70 | — | V | V _{GS} = 0V, I _D = 100μA |
| Zero Gate Voltage Drain Current | I _{DSS} | — | — | 1.0 | μA | V _{DS} = 60V, V _{GS} = 0V |
| Gate-Body Leakage | I _{GSS} | — | — | ±10 | nA | V _{GS} = ±15V, V _{DS} = 0V |
| ON CHARACTERISTICS (Note 3) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | 0.8 | 2.1 | 3.0 | V | V _{DS} = V _{GS} , I _D = 250μA |
| Static Drain-Source On-Resistance | R _{DS(ON)} | — | — | 5.0 | Ω | V _{GS} = 10V, I _D = 200mA V _{GS} = 4.5V, I _D = 50mA |
| | | — | — | 5.3 | | |
| Forward Transconductance | g _{FS} | 80 | — | — | mS | V _{DS} = 10V, I _D = 0.2A |
| DYNAMIC CHARACTERISTICS | | | | | | |
| Input Capacitance | C _{iss} | — | 22 | 40 | pF | V _{DS} = 10V, V _{GS} = 0V, f = 1.0MHz |
| Output Capacitance | C _{oss} | — | 11 | 30 | pF | |
| Reverse Transfer Capacitance | C _{rss} | — | 2.0 | 5.0 | pF | |
| SWITCHING CHARACTERISTICS | | | | | | |
| Turn-On Time | t _{on} | — | — | 10 | ns | V _{DD} = 25V, I _D = 0.5A, |
| Turn-Off Time | t _{off} | — | — | 10 | ns | V _{GS} = 10V, R _{GEN} = 50Ω |

- Notes:
1. Device mounted on FR-4 PCB 1.0 x 0.75 x 0.062 inch pad layout as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 2. No purposefully added lead. Halogen and Antimony Free.
 3. Short duration pulse test used to minimize self-heating effect.
 4. Product manufactured with Data Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.

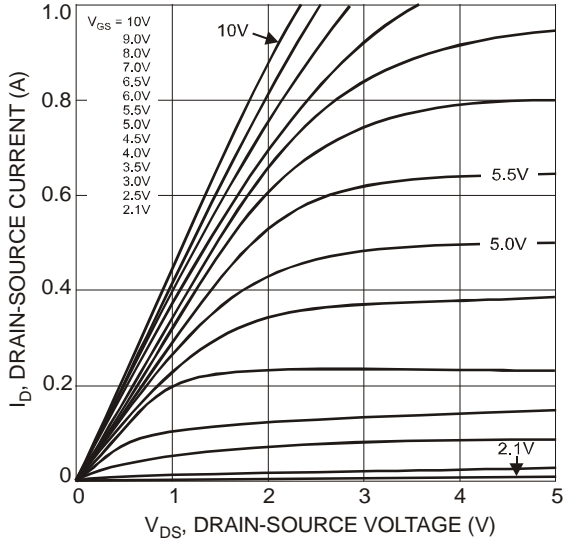


Fig. 1 On-Region Characteristics

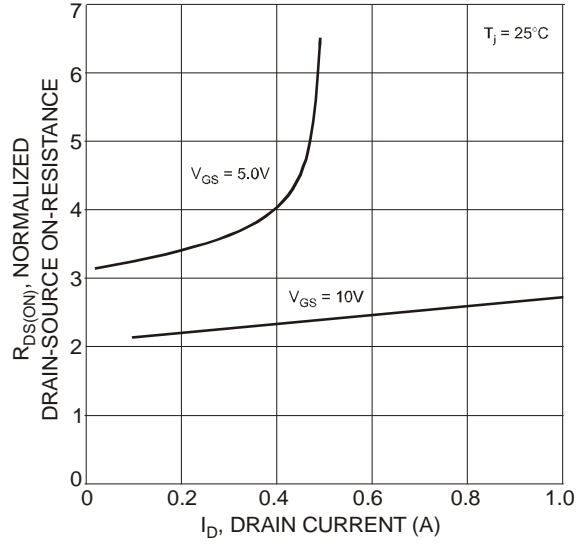


Fig. 2 On-Resistance vs. Drain Current

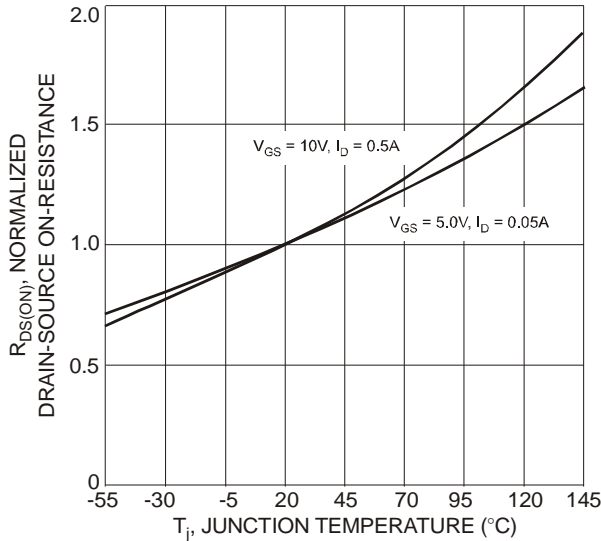


Fig. 3 On-Resistance vs. Junction Temperature

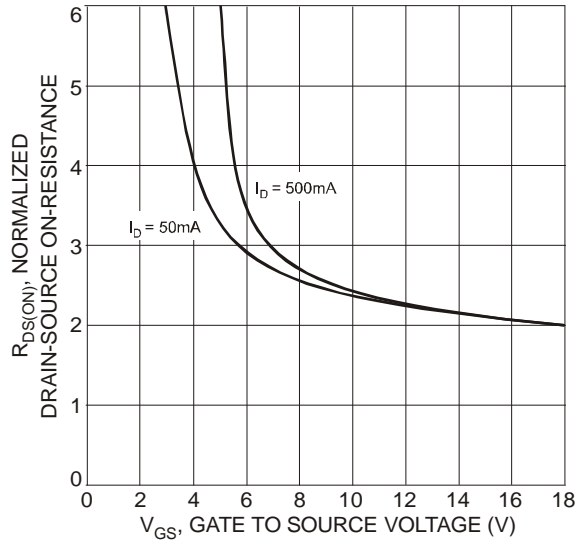


Fig. 4 On-Resistance vs. Gate-Source Voltage

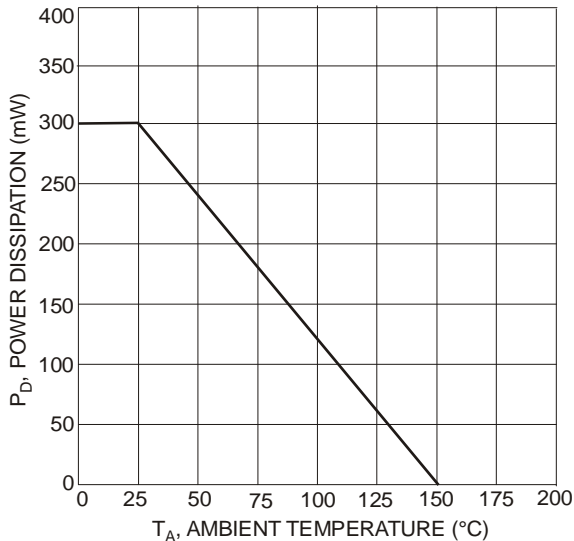


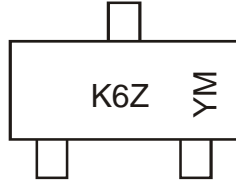
Fig. 5 Max Power Dissipation vs. Ambient Temperature

Ordering Information (Note 5)

| Part Number | Case | Packaging |
|-------------|--------|------------------|
| MMBF170-7-F | SOT-23 | 3000/Tape & Reel |

Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



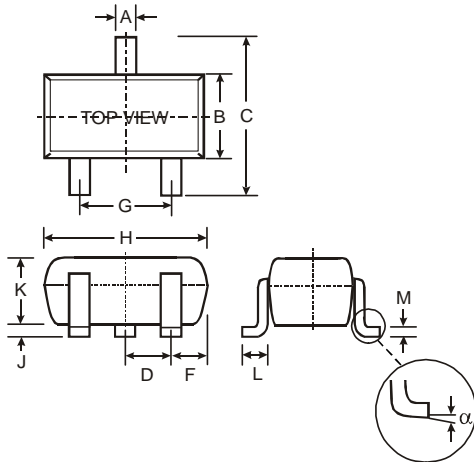
K6Z = Product Type Marking Code
 YM = Date Code Marking
 Y = Year ex: N = 2002
 M = Month ex: 9 = September

Date Code Key

| Year | 1998 | 1999 | 2000 | 2001 | 2002 | 2003 | 2004 | 2005 | 2006 | 2007 | 2008 | 2009 | 2010 | 2011 | 2012 |
|------|------|------|------|------|------|------|------|------|------|------|------|------|------|------|------|
| Code | J | K | L | M | N | P | R | S | T | U | V | W | X | Y | Z |

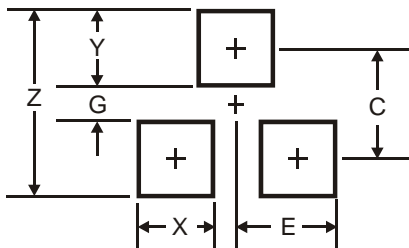
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | O | N | D |

Package Outline Dimensions



| SOT-23 | | |
|----------------------|-------|-------|
| Dim | Min | Max |
| A | 0.37 | 0.51 |
| B | 1.20 | 1.40 |
| C | 2.30 | 2.50 |
| D | 0.89 | 1.03 |
| F | 0.45 | 0.60 |
| G | 1.78 | 2.05 |
| H | 2.80 | 3.00 |
| J | 0.013 | 0.10 |
| K | 0.903 | 1.10 |
| L | 0.45 | 0.61 |
| M | 0.085 | 0.180 |
| α | 0° | 8° |
| All Dimensions in mm | | |

Suggested Pad Layout



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 3.4 |
| G | 0.7 |
| X | 0.9 |
| Y | 1.4 |
| C | 2.0 |
| E | 0.9 |

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